

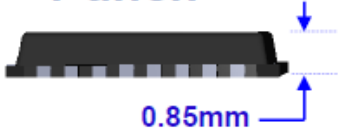

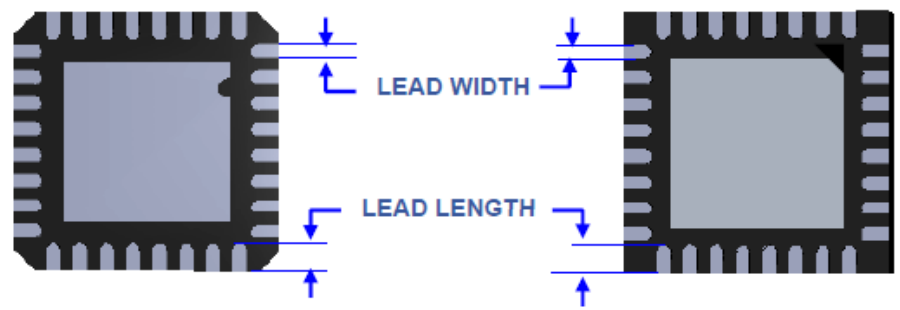
## Bill of Materials

Body Size	Material	FROM	TO
		Amkor	ASE
6x6 mm	Die Attach	Ablestik 8290	Hitachi EN-4900GC
	Wire	1.0 mil	0.8/1.0 mil
5x5 mm	Mold Compound	Sumitomo G700	Sumitomo G700
	Leadframe	C194	C194
4x4 mm	Die Attach	Ablestik 8290	Ablestik 8290
	Wire	1.0 mil	0.8/1.0 mil
	Mold Compound	Sumitomo G700	Sumitomo G700
	Leadframe	C194	C194

## Bill of Materials:

Package	Body Size	Material	Amkor	ASE-Korea	Remarks
LFCSP	7x7 mm	Die Attach	Ablestik 8290	Hitachi EN-4900GC	
		Wire	1.0 mil	0.8/1.0 mil	
	5x5 mm	Mold Compound	Sumitomo G700	Sumitomo G700	Same
		Leadframe	C194	C194	Same
	4x4 mm	Die Attach	Ablestik 8290	Ablestik 8290	Same
		Wire	1.0 mil	0.8/1.0 mil	
		Mold Compound	Sumitomo G700	Sumitomo G700	Same
		Leadframe	C194	C194	Same

## Package Dimensional Differences (Punch versus Sawn)

<p><b>Punch</b></p>  <p>0.85mm</p>	<p><b>Sawn</b></p>  <p>0.75mm</p>	<p><b>Package Thickness Difference</b></p>
 <p>LEAD WIDTH</p> <p>LEAD LENGTH</p>	<p>Aside from Epad dimension, change in Lead Width and Length may affect the Package to PCB solder contact. Maintaining the same dimensions avoids any risk.</p>	<p>Bottom Package Pin 1 indicator Change from half Moon to Chamfered Corner</p>

Qualification Data for LFCSP Devices at ASE Korea

QUALIFICATION RESULTS 48-LFCSP			
TEST	CONDITIONS	SAMPLE SIZE (LOT/QTY)	RESULTS
High Temperature Storage (HTS)	JESD22-A103, 150°C, 1000 hours	1 x 45	Pass
Temperature Cycle*	JESD22-A104, -65°C to +150°C, 2 cycle per hour, 500 cycles	3 x 77	Pass
Biased HAST *	JESD22-A110, 130°C, 85% RH, 96hrs	3 x 77	Pass
Autoclave*	JESD22-A102, 121°C, 100% RH, 96hrs	3 x 77	Pass
Solder Heat Resistance (SHR)*	ADI-0049	3 x 15	Pass
Electrostatic Discharge (ESD) Field Induced Charged Device Model (FICDM)	JESD22-C101, >500V	1 x 3	Pass

QUALIFICATION RESULTS 20-LFCSP			
TEST	CONDITIONS	SAMPLE SIZE (LOT/QTY)	RESULTS
High Temperature Storage (HTS)	JESD22-A103, 150°C, 1000 hours	1 x 40	Pass
Temperature Cycle*	JESD22-A104, -65°C to +150°C, 2 cycle per hour, 500 cycles	3 x 77	Pass
Biased HAST *	JESD22-A110, 130°C, 85% RH, 96hrs	3 x 77	Pass
Autoclave*	JESD22-A102, 121°C, 100% RH, 96hrs	3 x 77	Pass
Solder Heat Resistance (SHR)*	ADI-0049	3 x 15	Pass
Electrostatic Discharge (ESD) Field Induced Charged Device Model (FICDM)	JESD22-C101, >1500V	1 x 3	Pass

\*Preconditioned per JEDEC/IPC J-STD-020 MSL 3